



JFW  
PATENT  
8007-1116

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al. Conf. 1846

Application No. 10/594,221 Group 4145

Filed September 25, 2006 Examiner O. Ojurongbe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED  
PRODUCT THEREOF

AMENDMENT

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 29, 2008

Sir:

In response to the Official Action mailed April 29, 2008, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 6 of this paper.

An **Appendix** is attached which follows the signature page of this paper.